SOCKET ADAPTER TECHNOLOGY

High quality socket adapter solutions to reduce cost and maximize your programming yield.

Standard Socket Adapters

- Ideal for low to medium volume applications

- Supports the widest variety of device packages and thickness

- Proven socket adapter solutions

Medium Insertion Count (MIC) Socket Adapters

- Designed for medium to high volume applications

- Up to 50,000 insertions per socket

- Cost effective solution delivering high programming yields

High Insertion Count (HIC) Socket Adapters

- Highest quality components for high-volume programming applications

- Proprietary adapter design with up to 250,000 insertions per socket

- Delivers the industry's lowest cost per programmed device at ~ US $0.01

DATA I/O CORPORATION

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STANDARD SOCKET ADAPTER FEATURES

- Typical life is 5,000-10,000 insertions per socket
- Supports BGA, CSP, SO, TSOP, QFN, USON, QFP, PLCC, DIP
- FlashCORE III socket adapter capacity: up to 4 sockets per programmer
- LumenX socket adapter capacity: 1 socket per adapter and up to 8 adapters per programmer**
- Status LEDS
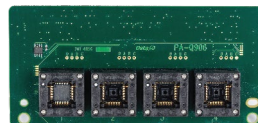
FLASHCORE III

LUMENX

MIDDLE INSERTION COUNT (MIC) SOCKET ADAPTER FEATURES

- Typical life is 50,000 insertions per socket
- Supports BGA, CSP, SO, QFN, USON
- FlashCORE III socket adapter capacity: Up to 4 sockets per programmer
- LumenX socket adapter capacity: 1 socket per adapter and up to 8 adapters per programmer**
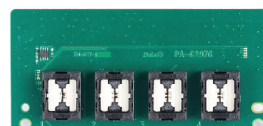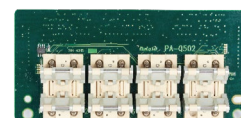- Status LEDS

FLASHCORE III

LUMENX

HIGH INSERTION COUNT (HIC) SOCKET ADAPTER FEATURES

- Typical life is 250,000 insertions per socket
- Typical yields are 99.8% and higher
- Supports BGA, CSP, WLCSP, SO, TSOP, QFN, USON, QFP
- FlashCORE III socket adapter capacity: up to 4 sockets per programmer
- LumenX socket adapter capacity: 1 socket per adapter and up to 8 adapters per programmer**
- Status LEDS
- Removable sockets

FLASHCORE III

LUMENX

Socket Type	Standard Burn In Socket		Medium Insertion Socket	High Insertion Socket
Device Package	BGA, WLCSP	QFP, TSOP, QFN, MLF	BGA, QFP, TSOP, MLF, WLCSP	BGA, WLCSP, QFP, TSOP, QFN, MLF
Insertions Per Socket (Mechanical Life Cycle)	5,000	10,000	50,000	250,000
Cost Per Device(US$)	0.04-0.08		~0.025	~0.01
Programming Applications	Low to medium		Medium to high volume	High volume
Typical Yield	97%		98.5%	99.8%
Maintenance Need	High	Medium	Low	Very Low
Maintenance Process	Compressed Air		Cleaning with DeoxIT® Gold Wipes and Nanotek Brush	Cleaning with DeoxIT® Gold Wipes and Nanotek Brush
Note	1) The performance characteristic of any socket in programming depends on a variety of factors including, but not limited to: solder alloy composites, tolerances, temperature, physical environment (dust) and cleanliness, and contact exposure time. 2) The mentioned cycles are indication for mechanical cycles.			

Standard and HIC adapter insertion count may vary depending on device or socket type. Please contact Data I/O Corporation for additional information.
**In some cases, a device may require larger adapters limiting the maximum number of adapters supported on LumenX to 4.*